

AMENDMENTS TO THE SPECIFICATION

Please amend the specification, beginning at page 1:

[0014] To achieve the above objects, there is provided an image sensor module according to one aspect of the present invention, comprising: a flexible PCB for transferring and transmitting electric signals; an image chip seated in a hollow area formed on a side surface of the flexible PCB; a predetermined transparent medium having a printed circuit of a predetermined pattern on an upper surface thereof; a first bump and a second bump formed on the upper surface of the transparent medium, the first bump being electrically connected to the chip pattern of the image sensor seated on the flexible PCB by bonding, and the second bump being electrically connected to the circuit of the flexible PCB; and epoxy resin ~~for molding~~ molded to a portion of a rear surface of the flexible PCB, on which an image chip is mounted.

Please amend the specification beginning at page 2:

[0019] There is also provided a method for fabricating an image sensor module according to one aspect of the present invention, the method comprising the steps of: forming a printed circuit of a predetermined pattern on an upper surface of a transparent medium; forming a first bump and a second bump on the upper surface of the transparent medium; first bonding the first bump with a pattern of an image chip so as to be electrically connected to each other; secondly bonding the second bump with the circuit of a flexible PCB so as to be electrically connected to each other; and molding a portion connected to a rear surface of the flexible PCB, on which the image chip is mounted, by means of epoxy resin.

Please amend the specification beginning at page 2:

[0024] According to another aspect of the present invention, there is provided an image sensor module comprising: a PCB for transferring and transmitting electric signals; an image chip seated in a hollow area formed on a side surface of the PCB; a predetermined transparent medium having a printed circuit of a predetermined pattern on an upper surface thereof; a first bump and a second bump formed on the upper surface of the transparent medium, the first bump being electrically

26 so as to be electrically connected, and epoxy resin 29 ~~for molding~~ molded to a portion of a rear surface of the PCB 26, on which the image chip is mounted.